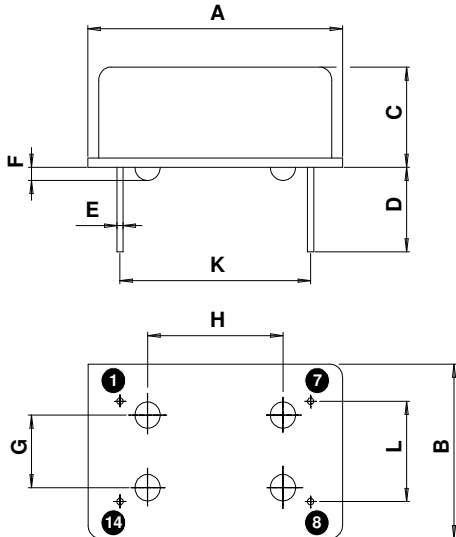


### Package dimension: Through holes version



#### Dimensions (typ.):

	In.	mm
A	0.80 ±0.003	20.14 ±0.08
B	0.493 ±0.003	12.52 ±0.08
C	0.307 ±0.008	7.8 ±0.2
D	0.25 ±0.002	6.35 ±0.5
E	0.018 ±0.0025	0.46 ±0.06
F	0.032 ±0.006	0.8 ±0.15
G	0.21 ±0.005	5.35 ±0.13
H	0.42 ±0.005	10.7 ±0.13
K	0.60 ±0.005	15.24 ±0.13
L	0.30 ±0.005	7.62 ±0.13

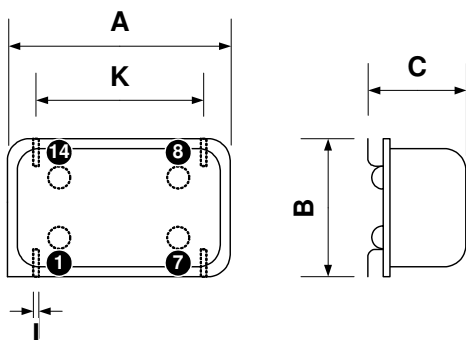
#### Pin Out:

1	Frequency adjustment
7	GND
8	Output
14	Vcc

### Recommended pins soldering:

235 °C ±5 °C, t = 10s ±0.5s  
(260 °C max for 5s max)

### Package dimension: SMD version (option D2):



#### Dimensions (typ.):

	In.	mm
A	0.80 ±0.003	20.14 ±0.08
B	0.493 ±0.003	12.52 ±0.08
C	0.374 ±0.008	9.5 ±0.2
K	0.60 ±0.005	15.24 ±0.13
I	0.018 ±0.0025	0.46 ±0.06

#### Pin Out:

1	Frequency adjustment
7	GND
8	Output
14	Vcc

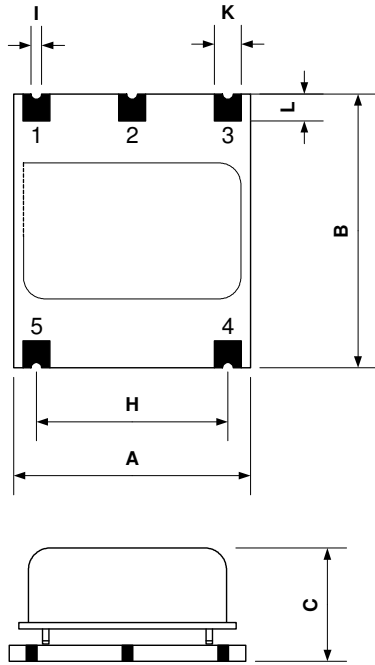
Date : October 2009 Revision No. : 3.6

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**In accordance with our policy of continuous development and improvement,  
we reserve the right to modify the design or the specifications of our products without prior notice.**

Headquarters:	Micro Crystal AG	Tel.	+41 32 655 82 82
	Mühlestrasse 14	Fax	+41 32 655 80 90
	CH-2540 Grenchen	Internet	www.microcrystal.ch
	Switzerland	Email	sales@microcrystal.ch

**Package dimension: SMD version (option D1):**



Dimensions (max.):

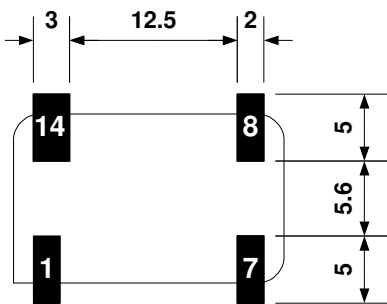
	In.	mm
A	0.87	22.0
B	1.00	25.4
C	0.41	10.5
H	0.70	17.8
I	∅ 0.04	∅ 1.0
K	0.10	2.5
L	0.10	2.5

Pin Out:

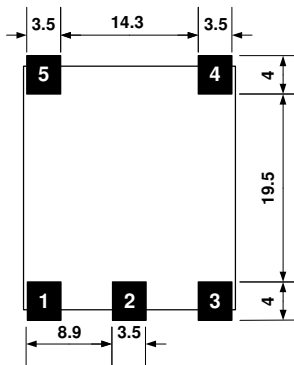
1	Frequency adjustment
2	NC
3	Vcc
4	Output
5	GND

**Recommended solder pad layout & soldering conditions:**

Solder pad layout: Option D2

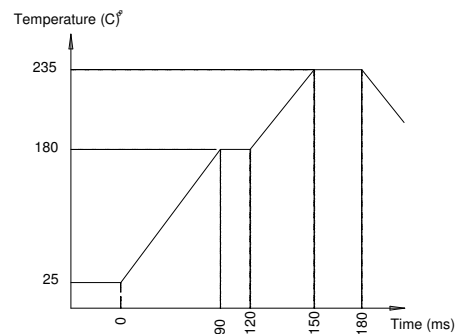


Solder pad layout: Option D1



Reflow soldering conditions

Reflow rate: 3°C/sec. max



Wave soldering: Temp. peak up to 260°C allowed for 5s (on pins)